

650V 75A Insulated Gate Bipolar Transistor
AKB65A075WHS

Description:

Gen 3 IGBT with soft, fast recovery full current rated anti-parallel Emitter Controlled diode, providing ultra-low conduction loss. They are designed for applications such as UPS, inverters, etc.

Features:

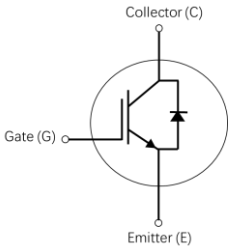
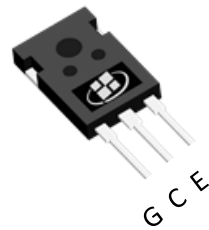
- Easy paralleling capability due to positive temperature coefficient in V_{CESAT}
- Low EMI
- Low Gate Charge
- Very soft, fast recovery full current anti-parallel diode
- Maximum junction temperature $T_{VJmax}=175^{\circ}C$
- RoHS compliant ^(Note 1)
- Halogen-free ^(Note 1)

Applications:

- Industrial UPS
- Charger
- Energy Storage
- Three-Phase Solar String Inverter

Key Performance Parameters:

Parameter	Value	Unit
V_{CE}	650	V
$V_{CESAT}, T_{VJ} = 25^{\circ}C$	1.4	V
I_C	75	A



Ordering Information:

Ordering Code	Package Type	Marking Code	Form	Packing
AKB65A075WHS	TO247-3L	B65A075WHS	Tube	300 per box

Maximum Ratings ($T_{VJ} = 25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
V_{CE}	Collector-Emitter Voltage	650	V
I_C	Collector Current - Continuous ($T_C = 25^{\circ}\text{C}$) ^(Note 1)	80	A
	Collector Current - Continuous ($T_C = 100^{\circ}\text{C}$)	80	A
I_{CM}	Collector Current - Pulsed ^(Note 2)	300	A
I_F	Diode Forward Current, Limited by T_{VJmax} ($T_C = 25^{\circ}\text{C}$)	80	A
	Diode Forward Current, Limited by T_{VJmax} ($T_C = 100^{\circ}\text{C}$)	80	A
I_{FM}	Diode Pulsed Current, - Pulsed ^(Note 2)	300	A
V_{GE}	Gate-Emitter Voltage	± 20	V
	Transient Gate-Emitter Voltage ($t_p \leq 10\mu\text{s}$, $D < 0.010$)	± 30	
P_D	Power Dissipation ($T_C = 25^{\circ}\text{C}$)	277	W
	Power Dissipation ($T_C = 100^{\circ}\text{C}$)	138	W
T_{VJ}	Operating Junction Temperature Range	-40 to +175	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	IGBT Thermal Resistance, Junction-to-Case, Steady-State	0.45	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Diode Thermal Resistance, Junction-to-Case, Steady-State	0.54	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient Steady State	40	$^{\circ}\text{C/W}$

Notes:

1. The max collector current rating is package limited
2. Repetitive rating: pulse width limited by maximum junction temperature

Electrical Characteristics ($T_{VJ} = 25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Static Characteristics						
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0\text{ V}, I_C = 0.2\text{ mA}$	650			V
V_{CESAT}	Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{ V}, I_C = 75\text{ A}$		1.40	1.75	V
		$V_{GE} = 15\text{ V}, I_C = 75\text{ A}, T_{VJ} = 125^{\circ}\text{C}$		1.58		
		$V_{GE} = 15\text{ V}, I_C = 75\text{ A}, T_{VJ} = 175^{\circ}\text{C}$		1.68		
V_F	Diode Forward Voltage	$V_{GE} = 0\text{ V}, I_F = 75\text{ A}$		1.50	1.90	V
		$V_{GE} = 0\text{ V}, I_F = 75\text{ A}, T_{VJ} = 125^{\circ}\text{C}$		1.63		
		$V_{GE} = 0\text{ V}, I_F = 75\text{ A}, T_{VJ} = 175^{\circ}\text{C}$		1.60		
$V_{GE(TH)}$	Gate-Emitter Threshold Voltage	$V_{CE} = V_{GE}, I_C = 0.75\text{ mA}$	3.2	4.0	4.8	V
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}$			50	μA
		$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_{VJ} = 175^{\circ}\text{C}$		3000		
I_{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{ V}, V_{CE} = 0\text{ V}$			± 100	nA
G_{FS}	Transconductance	$V_{CE} = 20\text{ V}, I_C = 75\text{ A}$		75		S
Dynamic Characteristics						
C_{ies}	Input Capacitance	$V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V},$ $F = 1\text{ MHz}$		4590		pF
C_{oes}	Output Capacitance			215		pF
C_{res}	Reverse Transfer Capacitance			23		pF
Q_G	Total Gate Charge	$V_{CC} = 520\text{ V}, I_C = 75\text{ A},$ $V_{GE} = 15\text{ V}$		177		nC
Q_{GE}	Gate-Emitter Charge			27		nC
Q_{GC}	Gate-Collector Charge			58		nC
L_E	Internal Emitter Inductance			13		nH
Switching Characteristics, Inductive Load ($T_{VJ} = 25^{\circ}\text{C}$)						
$T_{D(ON)}$	Turn On Delay Time	$V_{CC} = 400\text{ V}$ $I_C = 75\text{ A}$ $V_{GE} = 15\text{ V}$ $R_{Gon} = 18\ \Omega$ $R_{Goff} = 5.6\ \Omega$		55		ns
T_R	Rise Time			52		ns
$T_{D(OFF)}$	Turn Off Delay Time			158		ns
T_F	Fall Time			15		ns
E_{ON}	Turn On Energy			2.60		mJ
E_{OFF}	Turn Off Energy			0.88		mJ
E_{TOTAL}	Total Switching Energy			3.48		mJ

$T_{D(ON)}$	Turn On Delay Time	$V_{CC} = 400\text{ V}$ $I_C = 37.5\text{ A}$ $V_{GE} = 15\text{ V}$ $R_{Gon} = 18\ \Omega$ $R_{Goff} = 5.6\ \Omega$		53		ns
T_R	Rise Time			30		ns
$T_{D(OFF)}$	Turn Off Delay Time			184		ns
T_F	Fall Time			12		ns
E_{ON}	Turn On Energy			1.11		mJ
E_{OFF}	Turn Off Energy			0.44		mJ
E_{TOTAL}	Total Switching Energy			1.55		mJ

Diode Characteristics ($T_{VJ} = 25^\circ\text{C}$)

T_{RR}	Reverse Recovery Time	$V_R = 400\text{ V}, I_F = 75\text{ A},$ $di/dt = 1300\text{ A}/\mu\text{s}$		115		ns
Q_{RR}	Reverse Recovery Charge			3.3		μC
I_{RRM}	Peak Reverse Recovery Current			38		A
di_{rr}/dt	Diode Peak Rate of Fall of Reverse Recovery Current			1525		$\text{A}/\mu\text{s}$

T_{RR}	Reverse Recovery Time	$V_R = 400\text{ V}, I_F = 37.5\text{ A},$ $di/dt = 1200\text{ A}/\mu\text{s}$		158		ns
Q_{RR}	Reverse Recovery Charge			1.6		μC
I_{RRM}	Peak Reverse Recovery Current			36		A
di_{rr}/dt	Diode Peak Rate of Fall of Reverse Recovery Current			1123		$\text{A}/\mu\text{s}$

Switching Characteristics, Inductive Load ($T_{VJ} = 150^\circ\text{C}$)

$T_{D(ON)}$	Turn On Delay Time	$V_{CC} = 400\text{ V}$ $I_C = 75\text{ A}$ $V_{GE} = 15\text{ V}$ $R_{Gon} = 18\ \Omega$ $R_{Goff} = 5.6\ \Omega$		60		ns
T_R	Rise Time			51		ns
$T_{D(OFF)}$	Turn Off Delay Time			183		ns
T_F	Fall Time			39		ns
E_{ON}	Turn On Energy			3.31		mJ
E_{OFF}	Turn Off Energy			1.45		mJ
E_{TOTAL}	Total Switching Energy			4.76		mJ

$T_{D(ON)}$	Turn On Delay Time	$V_{CC} = 400\text{ V}$ $I_C = 37.5\text{ A}$ $V_{GE} = 15\text{ V}$ $R_{Gon} = 18\text{ }\Omega$ $R_{Goff} = 5.6\text{ }\Omega$		50		ns
T_R	Rise Time			33		ns
$T_{D(OFF)}$	Turn Off Delay Time			228		ns
T_F	Fall Time			29		ns
E_{ON}	Turn On Energy			1.73		mJ
E_{OFF}	Turn Off Energy			0.80		mJ
E_{TOTAL}	Total Switching Energy			2.53		mJ

Diode Characteristics ($T_{VJ} = 150^{\circ}\text{C}$)

T_{RR}	Reverse Recovery Time	$V_R = 400\text{ V}, I_F = 75\text{ A},$ $di/dt = 1300\text{ A}/\mu\text{s}$		114		ns
Q_{RR}	Reverse Recovery Charge			5.5		μC
I_{RRM}	Peak Reverse Recovery Current			58		A
di_{rr}/dt	Diode Peak Rate of Fall of Reverse Recovery Current			1900		$\text{A}/\mu\text{s}$

T_{RR}	Reverse Recovery Time	$V_R = 400\text{ V}, I_F = 37.5\text{ A},$ $di/dt = 1250\text{ A}/\mu\text{s}$		175		ns
Q_{RR}	Reverse Recovery Charge			3.7		μC
I_{RRM}	Peak Reverse Recovery Current			55		A
di_{rr}/dt	Diode Peak Rate of Fall of Reverse Recovery Current			2382		$\text{A}/\mu\text{s}$

Electrical Characteristics Diagrams

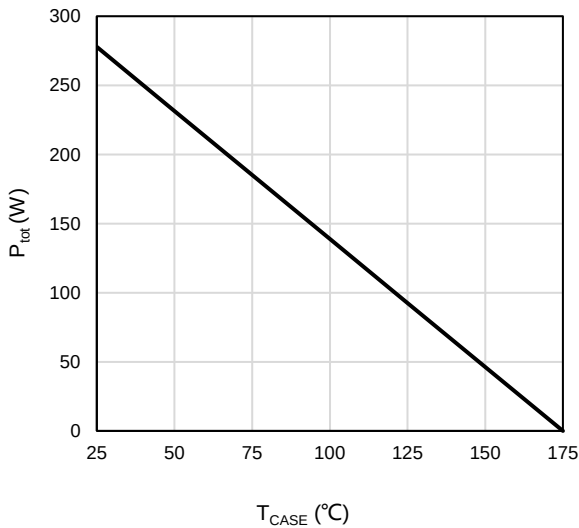


Figure 1: Power De-rating

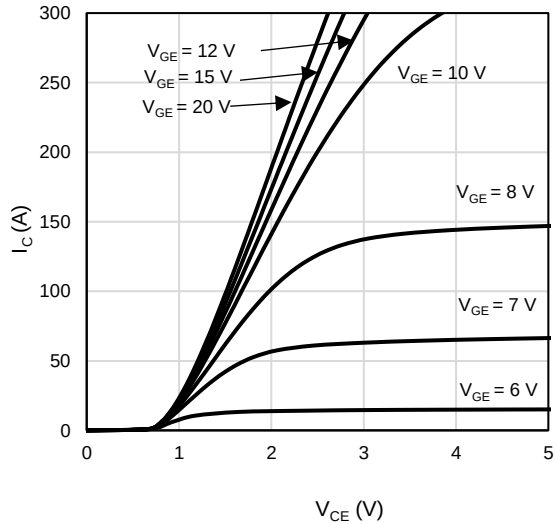


Figure 2: Typical Output Characteristics (T_{VJ} = 25°C)

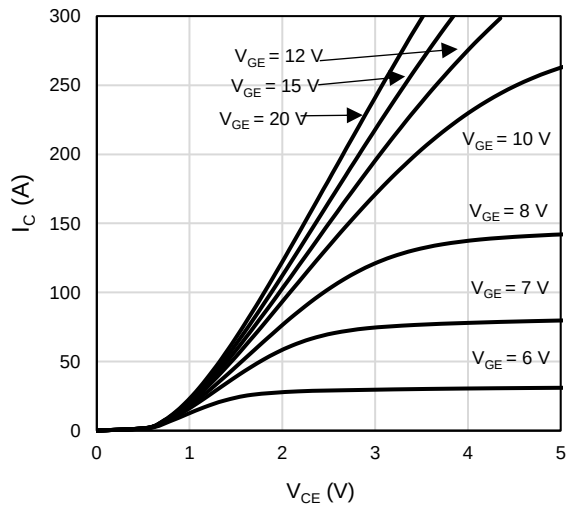


Figure 3: Typical Output Characteristics (T_{VJ} = 150°C)

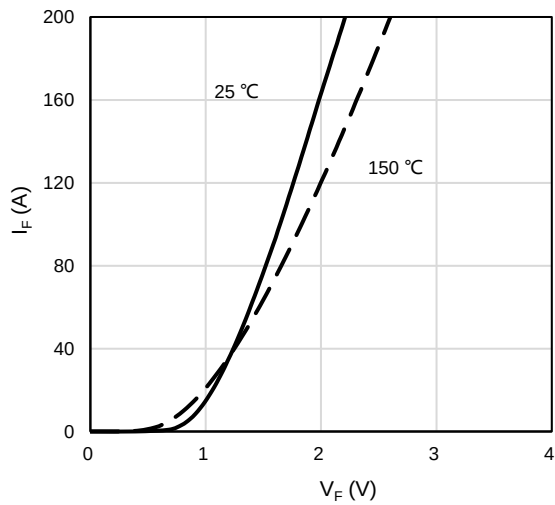


Figure 4: Diode Forward Current Characteristics

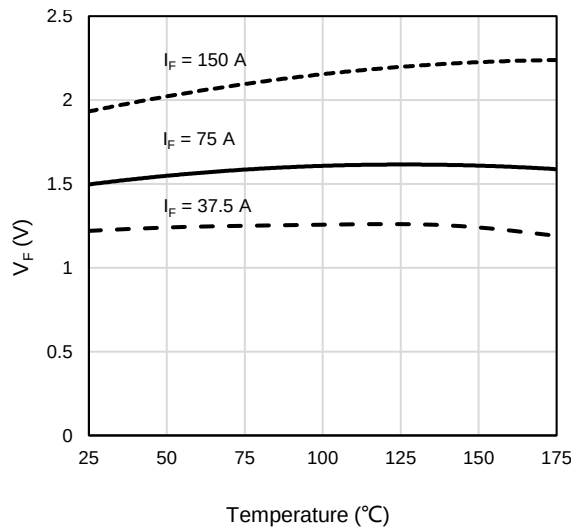


Figure 5: Diode Forward Voltage vs. Junction Temperature

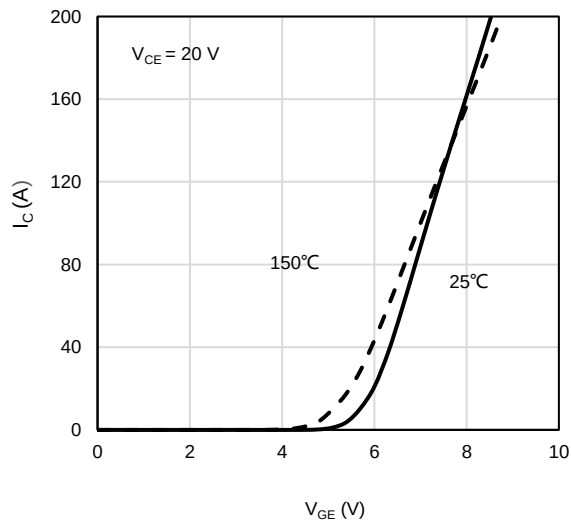


Figure 6: Transfer Characteristics

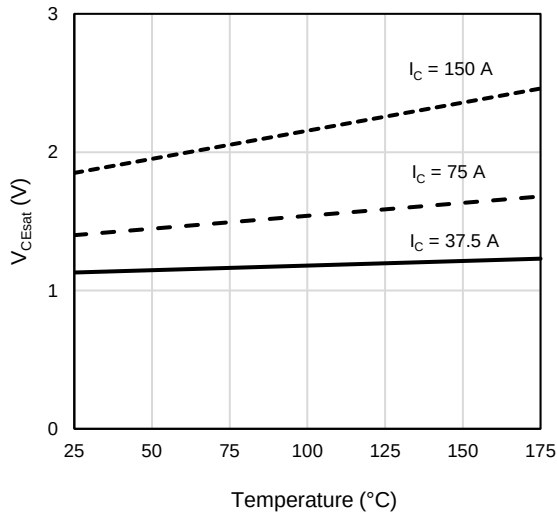


Figure 7: Collect-emitter saturation voltage vs. Junction Temperature

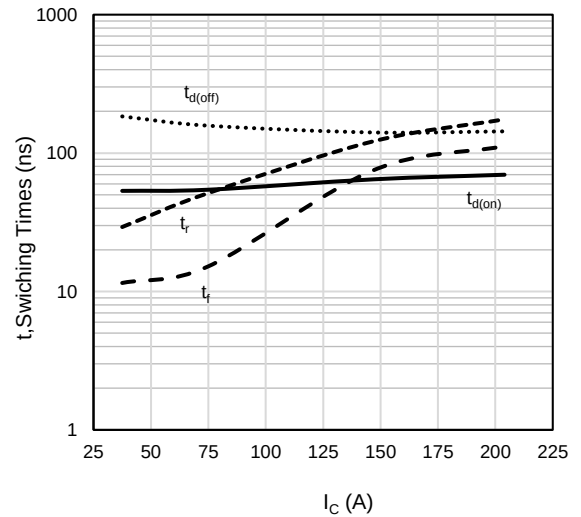


Figure 8: Switching Times vs. Collector Current

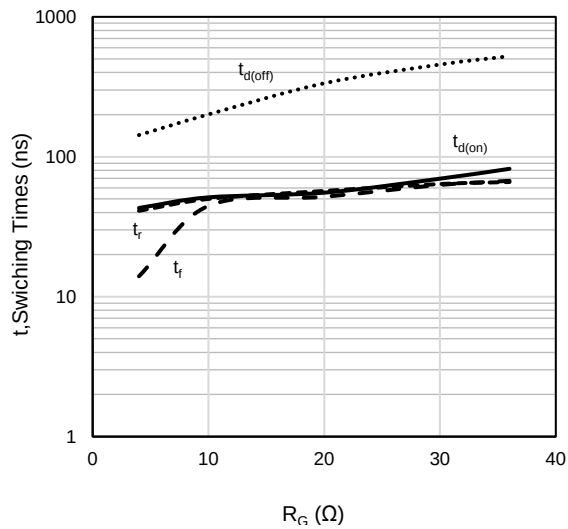


Figure 9: Switching Times vs. Gate Resistor

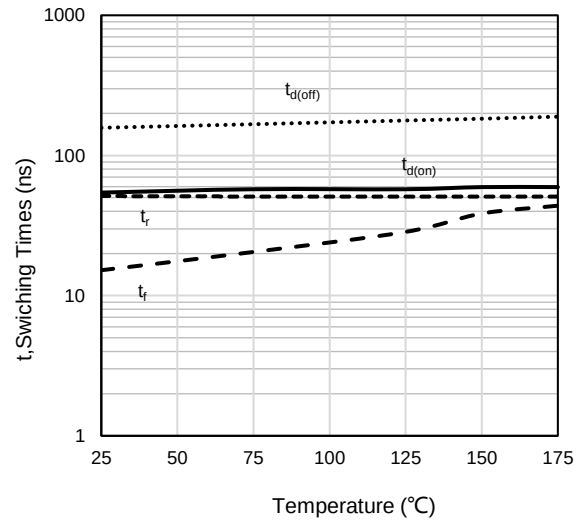


Figure 10: Switching Times vs. Junction Temperature

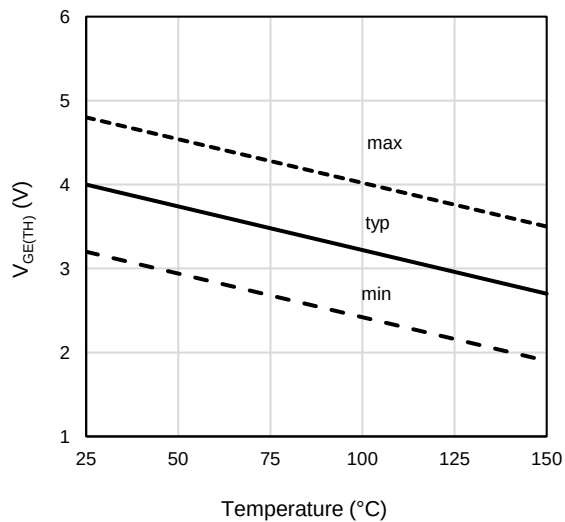


Figure 11: Threshold voltage vs. Junction Temperature

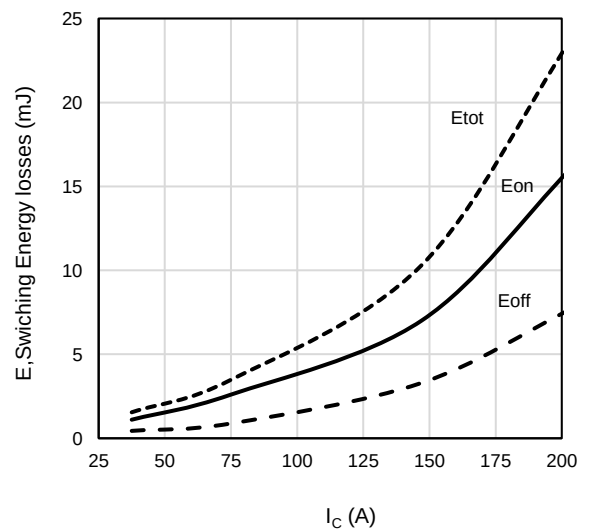


Figure 12: Switching Energy losses vs. Collector Current

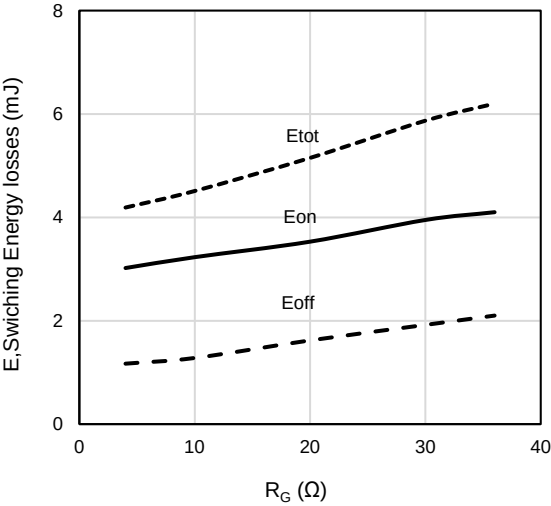


Figure 13: Switching Energy losses vs. Gate Resistor

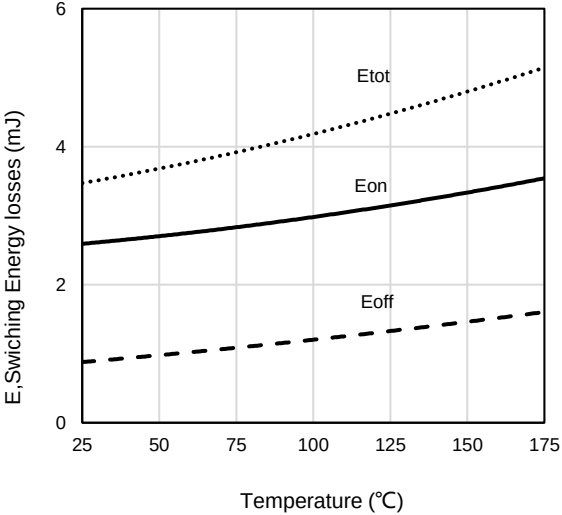


Figure 14: Switching Energy losses vs. Junction Temperature

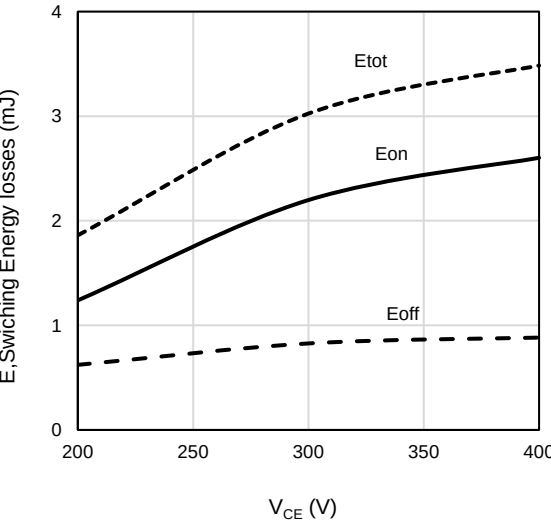


Figure 15: Switching Energy losses vs. Collector Emitter Voltage

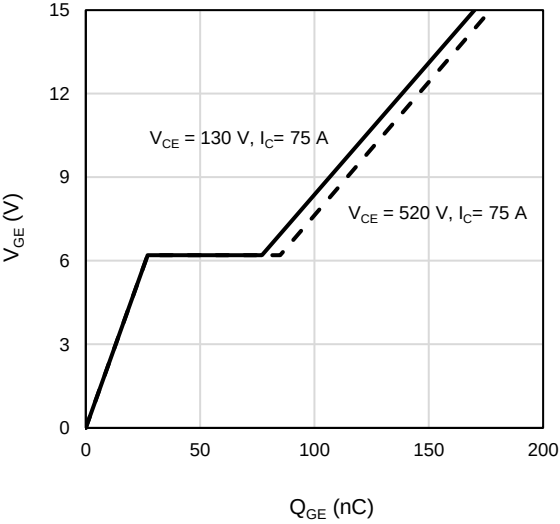


Figure 16: Gate-Charge Characteristics

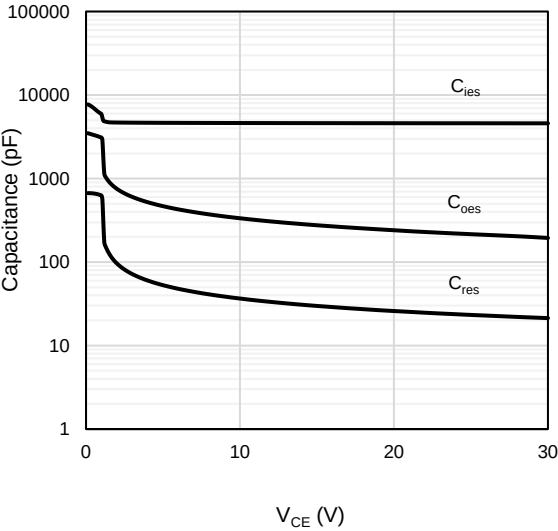


Figure 17: Capacitance Characteristics

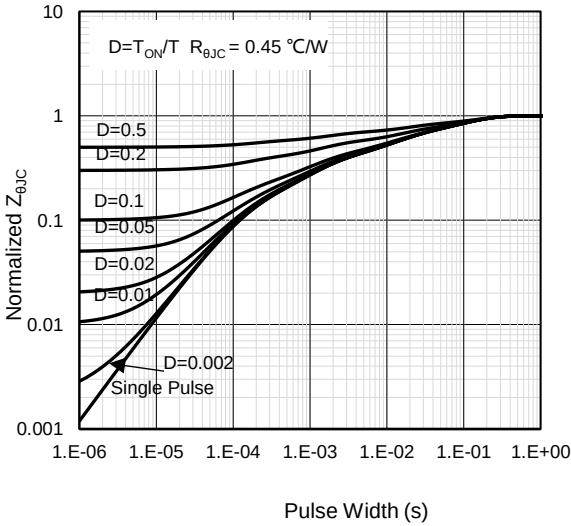


Figure 18: Normalized Maximum IGBT Transient Thermal Impedance

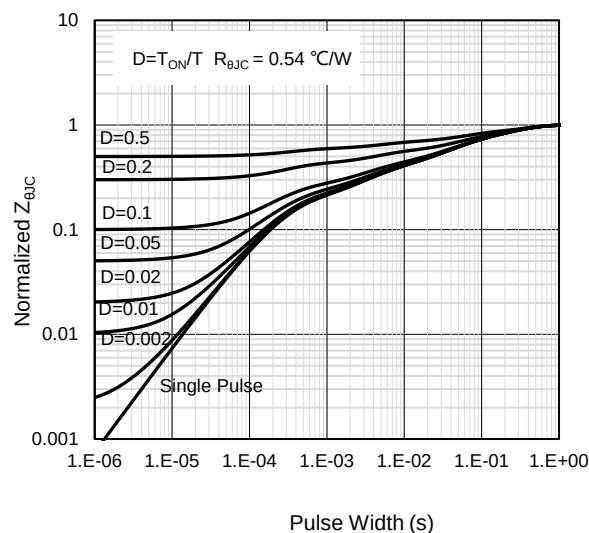


Figure 19: Normalized Maximum Diode Transient Thermal Impedance

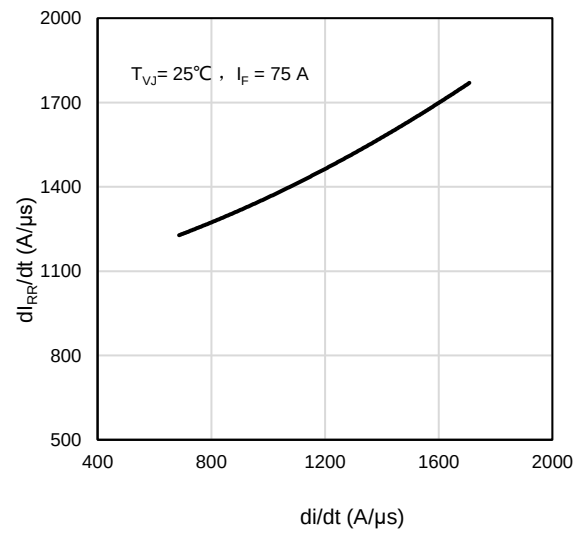


Figure 20: Diode Peak Rate of Fall of Reverse Recovery Current vs. Diode Current Slope

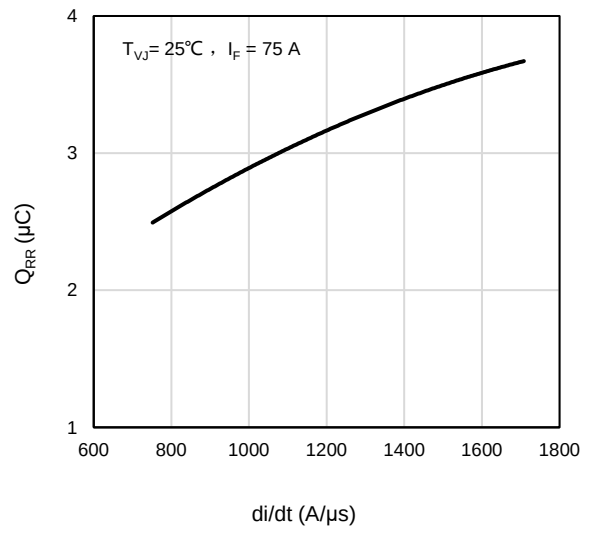


Figure 21: Reverse Recovery Charge vs. Diode Current Slope

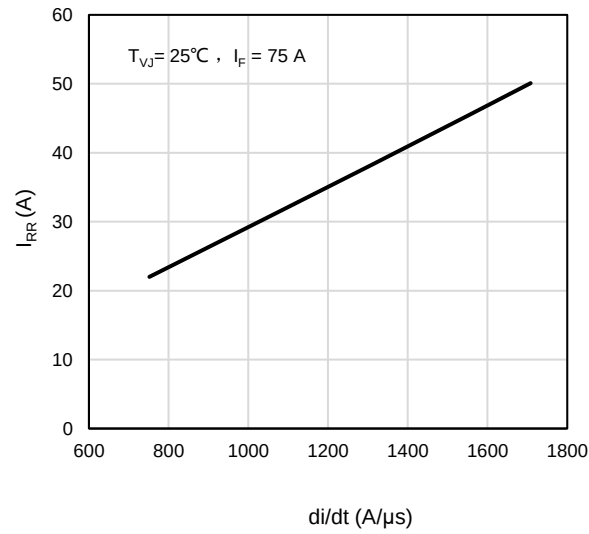


Figure 22: Reverse Recovery Current vs. Diode Current Slope

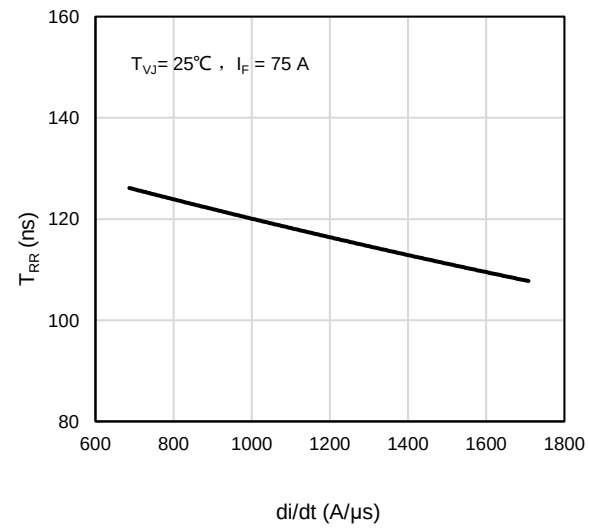
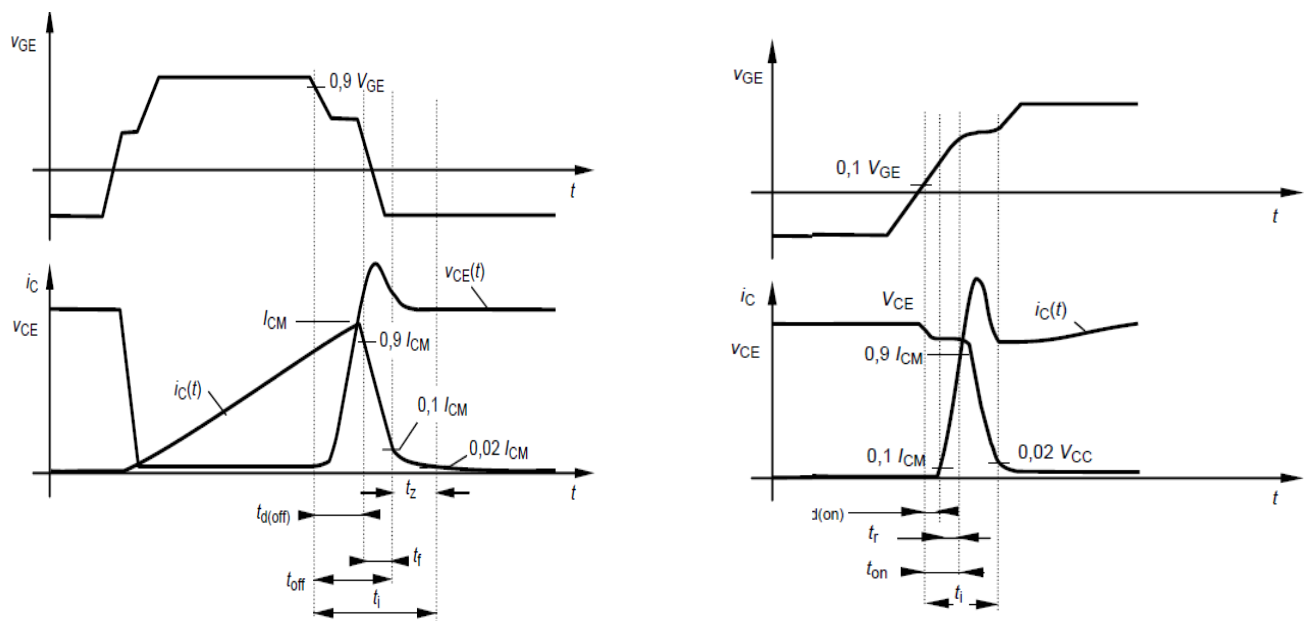


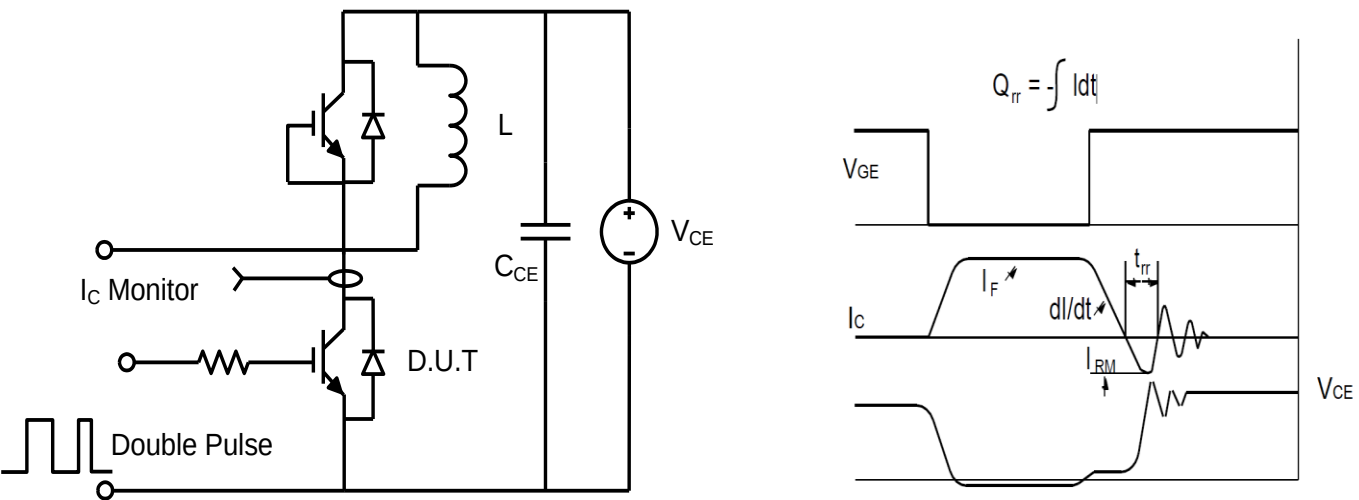
Figure 23: Reverse Recovery Time vs. Diode Current Slope

Test Circuit and Waveform

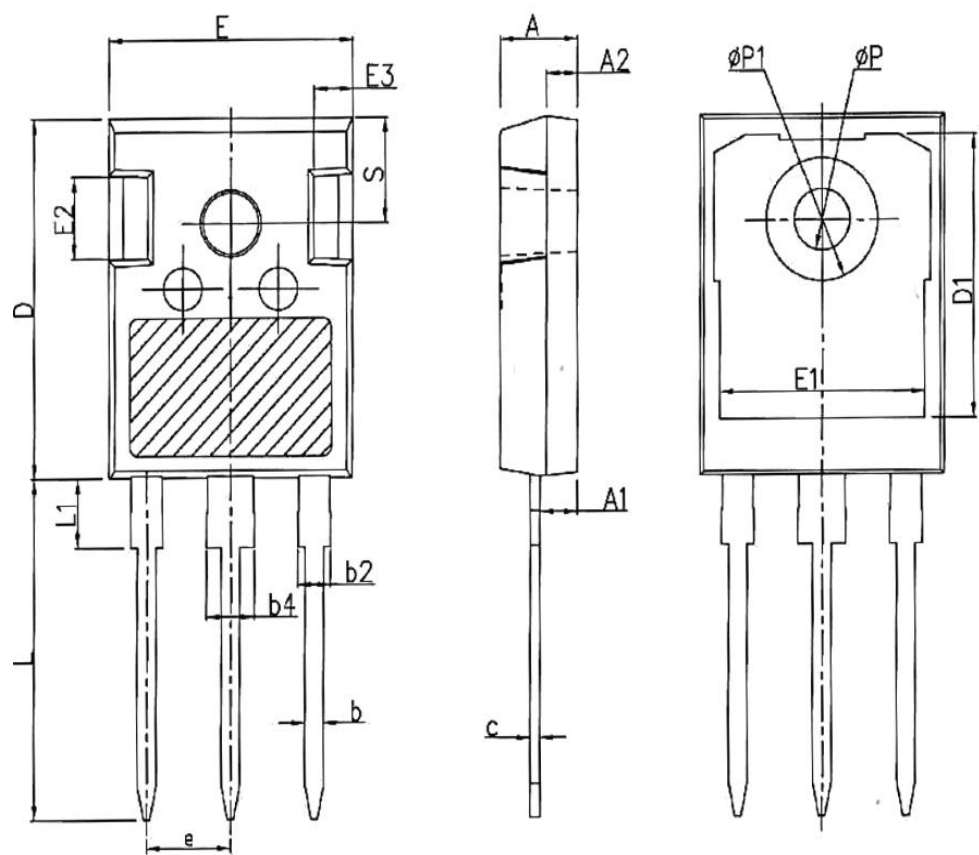
Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outlines



SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
ΦP	3.40	3.60	3.80
ΦP1	-	-	7.30
S	6.15BSC		

Marking Information



B65A075WHS

XXXXXXX

Note:

B65A075WHS = Product Name Code

XXXXXXX = Date code

Contact ALKAIDSEMI sales for detail information



Revision History

Revision	Released	Remark
Rev.1.0	2023	Initial Release

Disclaimer

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Alkaidsemi assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.